

Raise3D DF2 Technical Specifications

The Raise3D DF2 solution is a Digital Light Printing (DLP) system offering speed, quality, exceptional reliability and efficient workflow via RFID. It is designed for engineering prototyping, manufacturing aids, and low-volume production using a wide variety of high-performance

Printer	Raise3D DF2
Printer Hardware	<p>Print Technology DLP</p> <p>Build Volume (W × D × H) 200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch)</p> <p>XY Pixel Size 78.5 micron</p> <p>XY Resolution 2560 × 1440</p> <p>Max Z Workload 12 kg</p> <p>Layer Height 50-100 micron</p> <p>Max Printing Speed 25 mm/h (0.1 mm per layer)</p> <p>Resin Level Detection Yes</p> <p>Auto Resin Refill Yes</p> <p>Control Panel Touch Screen (1920 × 720, Magic Layout)</p> <p>Level Calibration Calibrated in Factory</p> <p>Chamber Heating Yes (Max 40°C)</p>
Resins (Available Options)	<p>Raise3D Standard White</p> <p>Raise3D High Detail Apricot</p> <p>Raise3D Tough 2K Grey</p> <p>Raise3D Rigid 3K Grey</p> <p>Raise3D High Clear Coming Soon</p> <p>Raise3D High Temperature Coming Soon</p> <p>Open Resin Program Coming Soon</p>
Software and Network	<p>Connectivity Wi-Fi, LAN, USB port × 2, Live camera</p> <p>Network Ethernet, Wireless 802.11 b/g/n</p> <p>Slicing Software ideaMaker</p> <p>Remote Management Software RaiseCloud</p> <p>Supported File Types STL/ OBJ/ 3MF/ OLTP</p> <p>Supported OS WINDOWS/ macOS/ LINUX</p>
Operation and Shipping	<p>Power Supply Input 100-240VAC, 50/60 Hz 230V @ 3.3A</p> <p>Operating Ambient Temperature 15 - 30°C, 10 - 90% RH Non-Condensing (HOLD)</p> <p>Storage Temperature -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD)</p> <p>Machine Size (W × D × H) 450 × 400 × 730 mm (17.7 × 15.7 × 28.7 inch)</p> <p>Weight 40 kg (Net Weight) 59.4 kg (Gross Weight)</p> <p>Shipping Dimensions 710 × 595 × 980 mm (28.0 × 23.4 × 38.6 inch)</p>